

**Low VF Glass Passivated Bridge Rectifiers**  
玻璃钝化低功耗整流桥

**Reverse Voltage - 600 Volts**  
反向电压 600V  
**Forward Current - 10 Amperes**  
正向电流 10A

**Features 特征**

- Glass passivated chip 玻璃钝化芯片
- Low forward voltage drop 正向压降低
- Ideal for printed circuit board 适用于印刷电路板中
- High surge current capability 高的浪涌能力

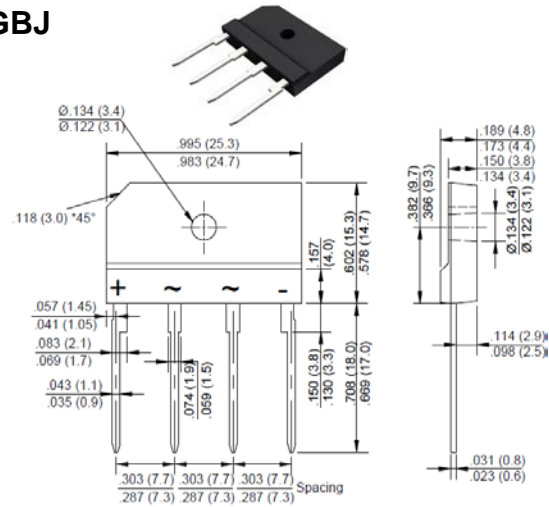
**Mechanical Data 外观信息**

- Polarity: Symbol marked on body 极性: 标志在产品的本体上
- Mounting position: Any 安装位置: 任何位置

**Applications 应用**

- General purpose use in AC/DC bridge full wave rectification, for SMPS, lighting ballaster, adapter, etc.  
一般应用于交流/直流桥式全波整流, 如: 开关电源, 照明镇流器、适配器等。

4GBJ



Package Outline Dimensions in Inches (Millimeters)

封装外观尺寸单位英寸 (毫米)

**Maximum Ratings and Electrical Characteristics 最大额定值及电气特性**

Rating at 25°C ambient temperature unless otherwise specified. 环境温度25°C, 除非特别说明。  
Single phase, half wave, 60Hz, resistive or inductive load. 单相半波, 60Hz, 阻性或感性负载。  
For capacitive load, derate current by 20%. 对于电容性负载, 降低20%的额定电流。

Characteristics 特性	Symbol 符号	4GBJ1006F	Unit 单位
Maximum Repetitive Peak Reverse Voltage 最大重复峰值反向电压	V <sub>RRM</sub>	600	V
Maximum RMS Voltage 最大有效反向电压	V <sub>RMS</sub>	420	V
Maximum DC Blocking Voltage 最大直流阻断电压	V <sub>DC</sub>	600	V
Maximum Average Forward Rectified Current (with heatsink Note 2) 最大正向平均整流电流 @ T <sub>c</sub> =100°C (without heatsink)	I <sub>(AV)</sub>	10.0 3.0	A
Peak Forward Surge Current, 8.3mS Single Half Sine-Wave, Superimposed on Rated Load (JEDEC Method) 8.3mS单一正弦半波叠加在额定负载上的浪涌能力 (JEDEC方法)	I <sub>FSM</sub>	210	A
I <sup>2</sup> t Rating for Fusing (t<8.3mS) 熔断额定值 (t<8.3mS)	I <sup>2</sup> t	183	A <sup>2</sup> s
Peak Forward Voltage per Diode at 5A DC 单个二极管在5A电流下的正向峰值电压	V <sub>F</sub>	0.95	V
Maximum DC Reverse Current at Rated @ T <sub>J</sub> =25°C DC Blocking Voltage per Diode @ T <sub>J</sub> =125°C 单个二极管在额定直流电压下的最大反向直流电流	I <sub>R</sub>	5.0 500	μA
Typical Junction Capacitance per Diode (Note1) 典型结电容 (备注1)	C <sub>J</sub>	55	pF
Typical Thermal Resistance to Ambient (without heatsink) 结到环境的典型热阻值 (不带散热片)	R <sub>θJA</sub>	24	°C/W
Typical Thermal Resistance to case (with heatsink (Note2)) 结到壳的典型热阻值 (带散热片, 备注2)	R <sub>θJC</sub>	1.4	°C/W
Typical Thermal Resistance to lead (without heatsink) 结到引线的典型热阻值 (不带散热片)	R <sub>θJL</sub>	3	°C/W
Operating Junction Temperature Range 结温工作范围	T <sub>J</sub>	-55 to +150	°C
Storage Temperature Range 储存温度范围	T <sub>STG</sub>	-55 to +150	°C

Notes: 1. Measured at 1.0 MHz and applied reverse voltage of 4.0V DC. 在 1.0MHz 下和反向电压为 4.0V DC 下测试。  
2. Device mounted on 150mm\*150mm\*1.6mm Cu plate heatsink. 安装在 150mm\*150mm\*1.6mm Cu 的散热片上。  
3. The typical data above is for reference only 典型值仅供参考。

Fig. 1 - Forward Current Derating Curve

图1 正向电流降额曲线

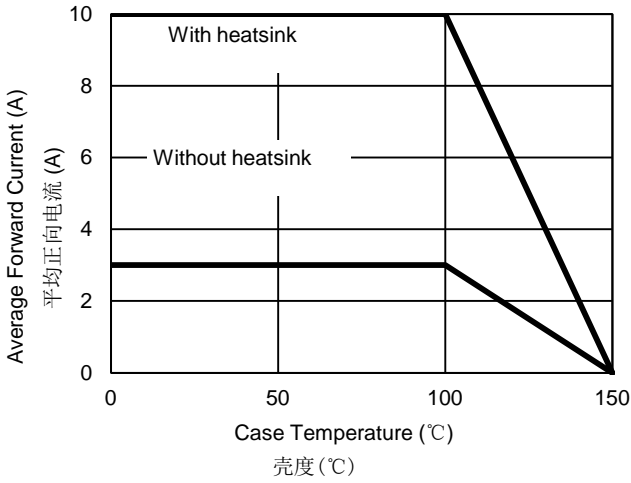


Fig. 2 - Maximum Non-Repetitive Surge Current

图2 最大不重复正向浪涌曲线

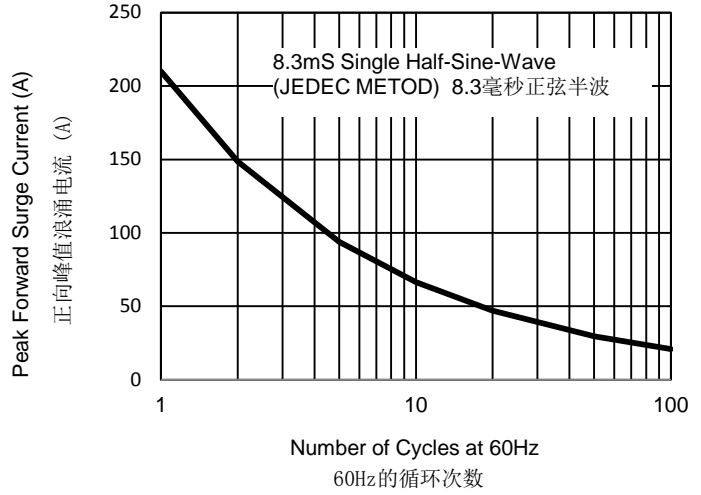


Fig. 3 - Typical Reverse Characteristics

图3 典型的反向特性

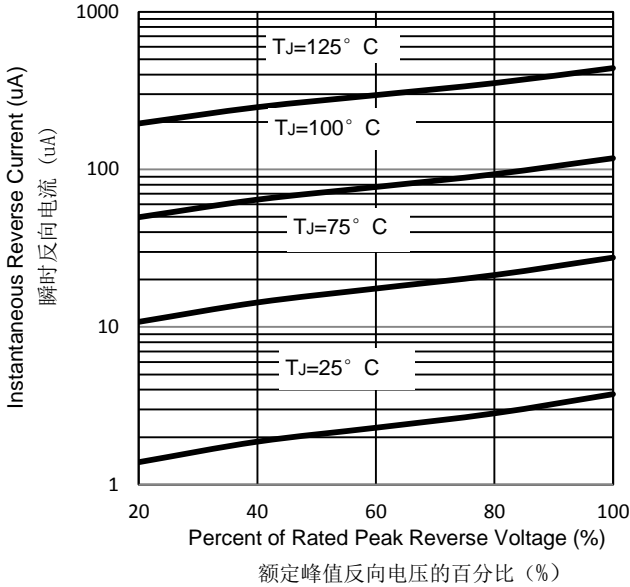


Fig. 4 - Typical Forward Characteristics

图4 典型的正向特性

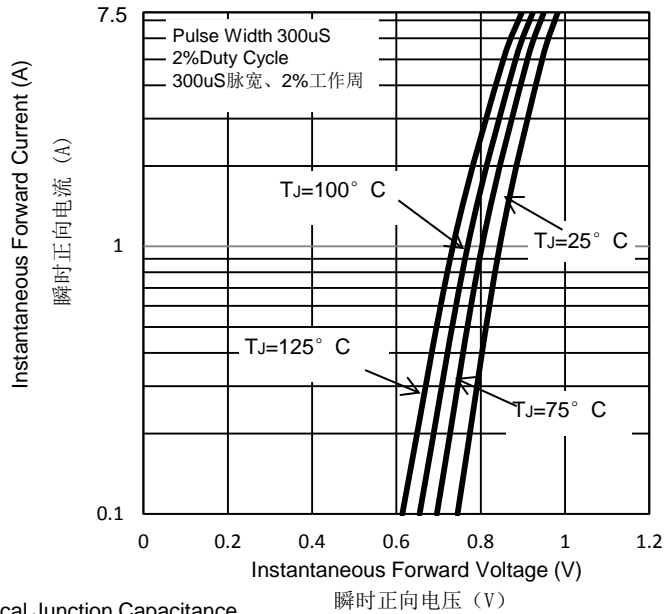
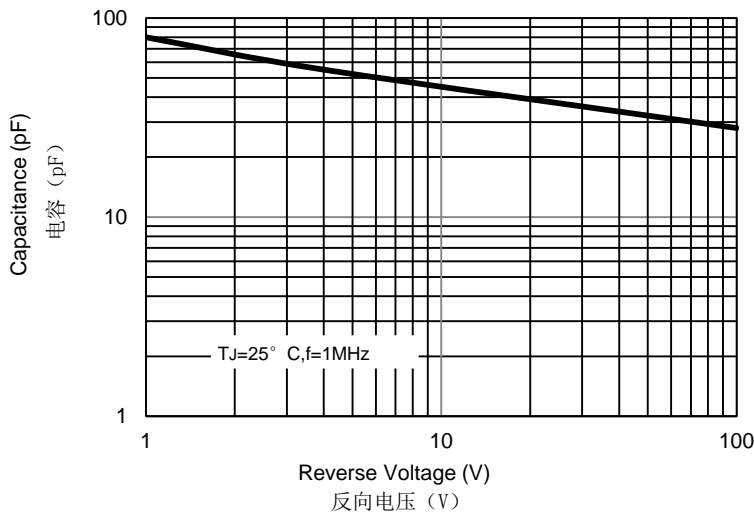


Fig. 5 - Typical Junction Capacitance

图5 典型的结电容



The curve above is for reference only. 曲线图仅供参考。



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